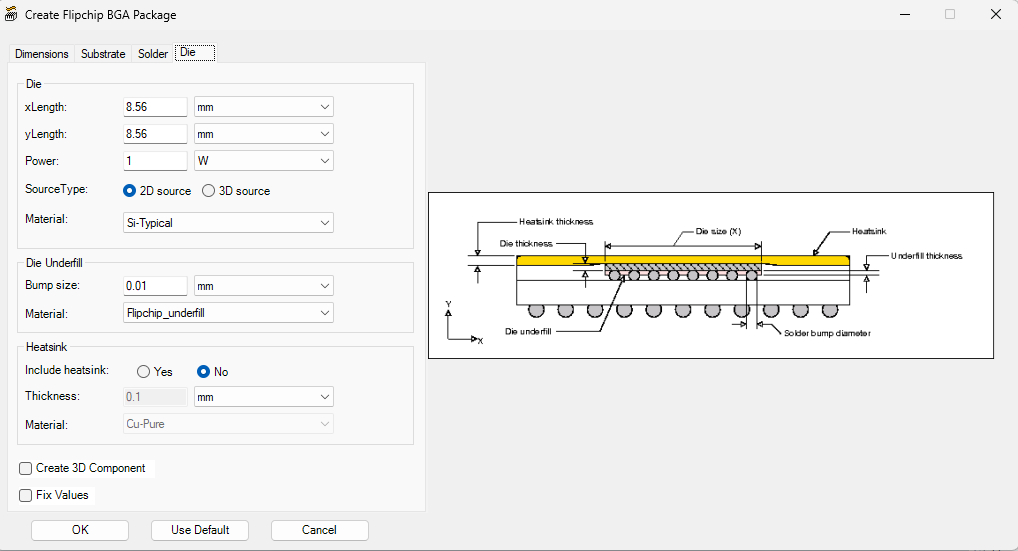
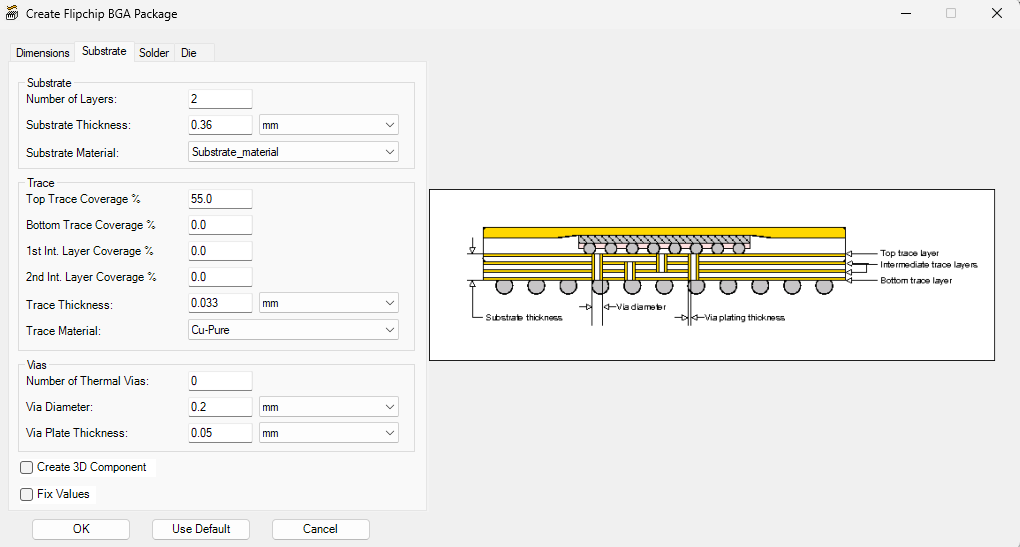
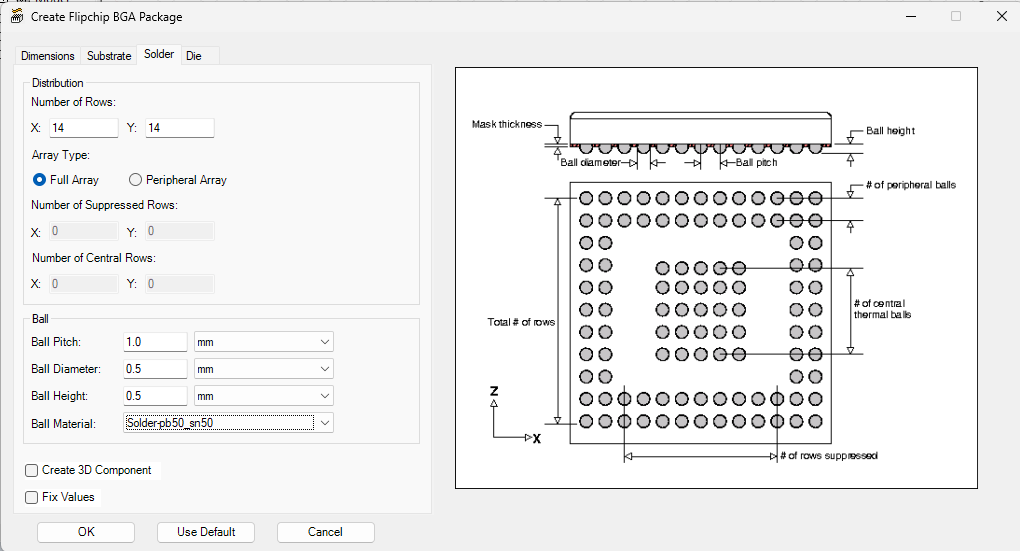
Semiconductor Packaging Module 3

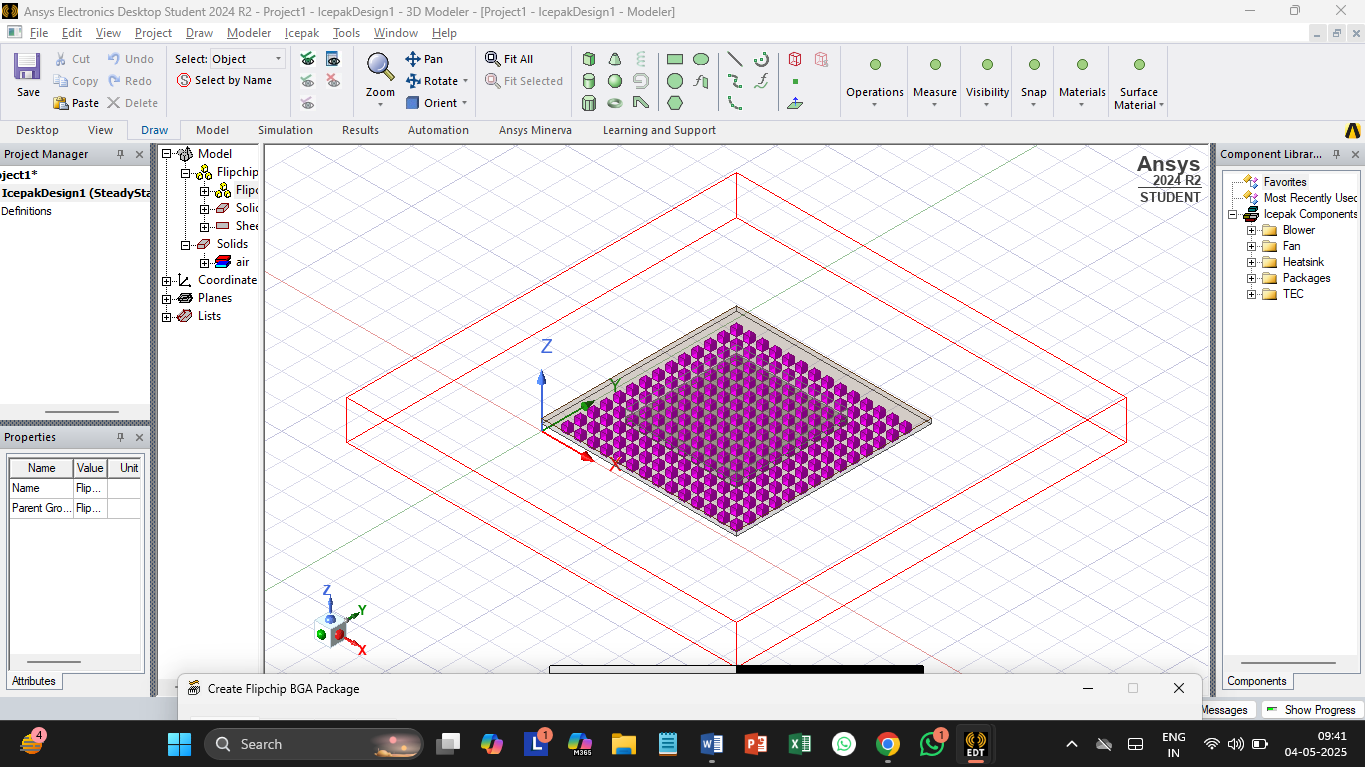
# Lesson 1

# Lesson 2





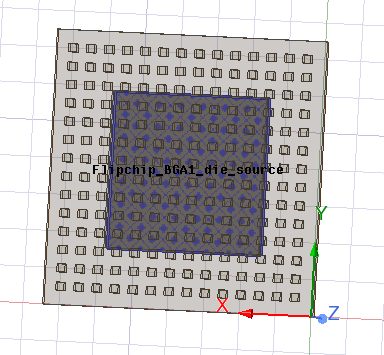


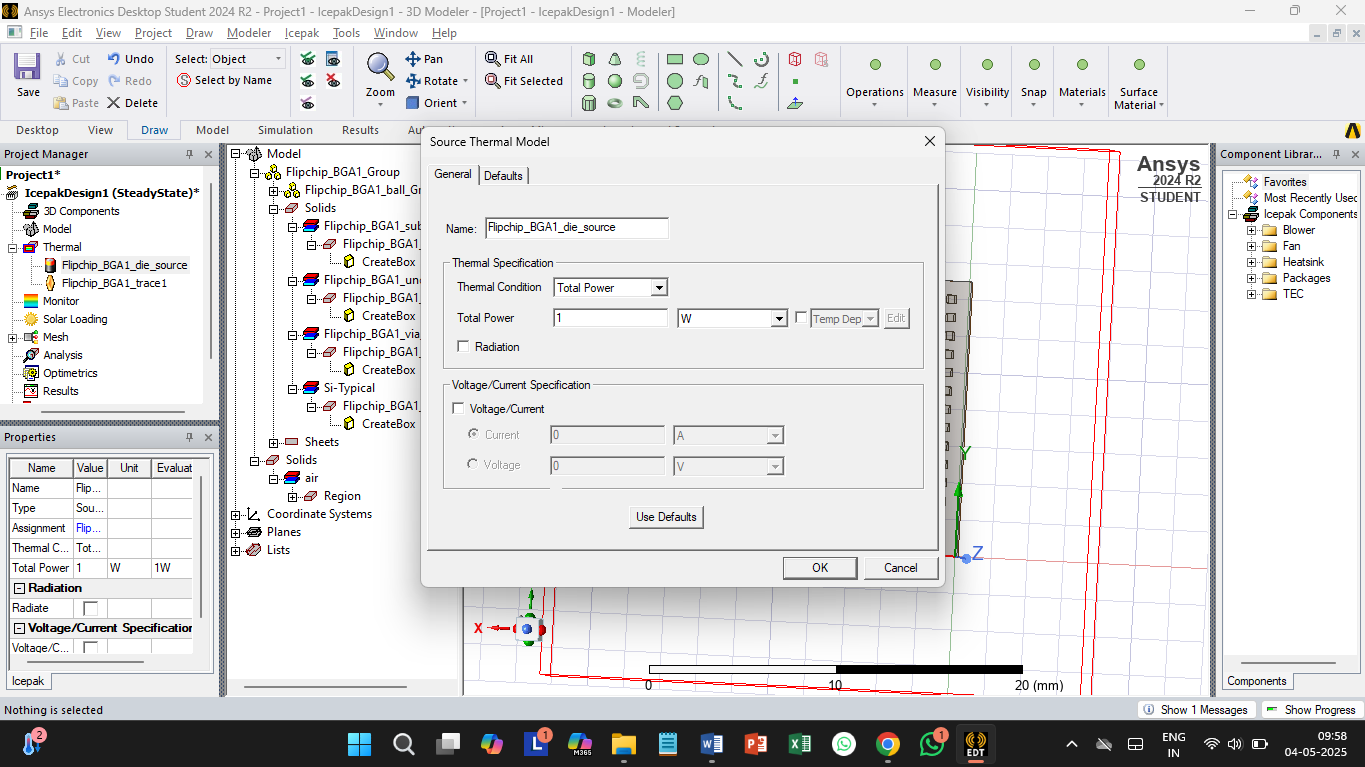


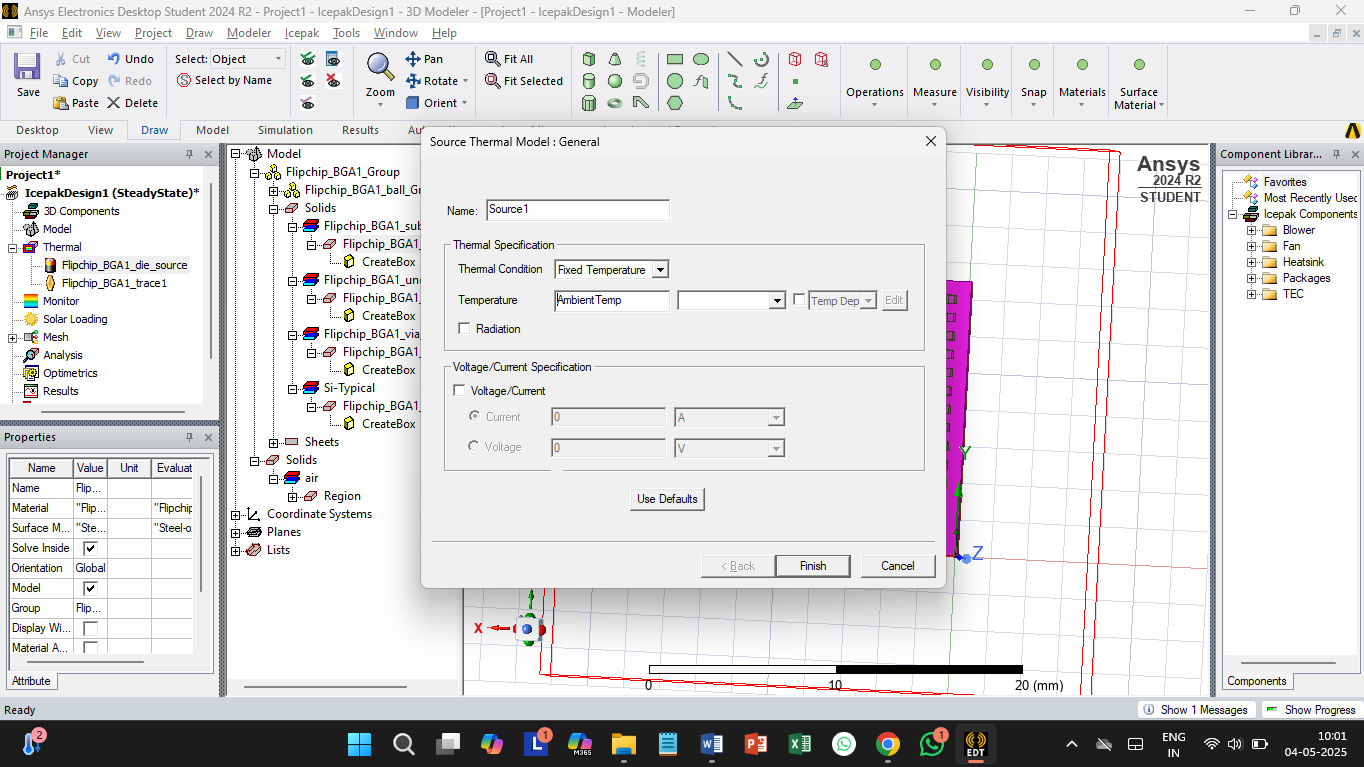
Showing different parts of the model

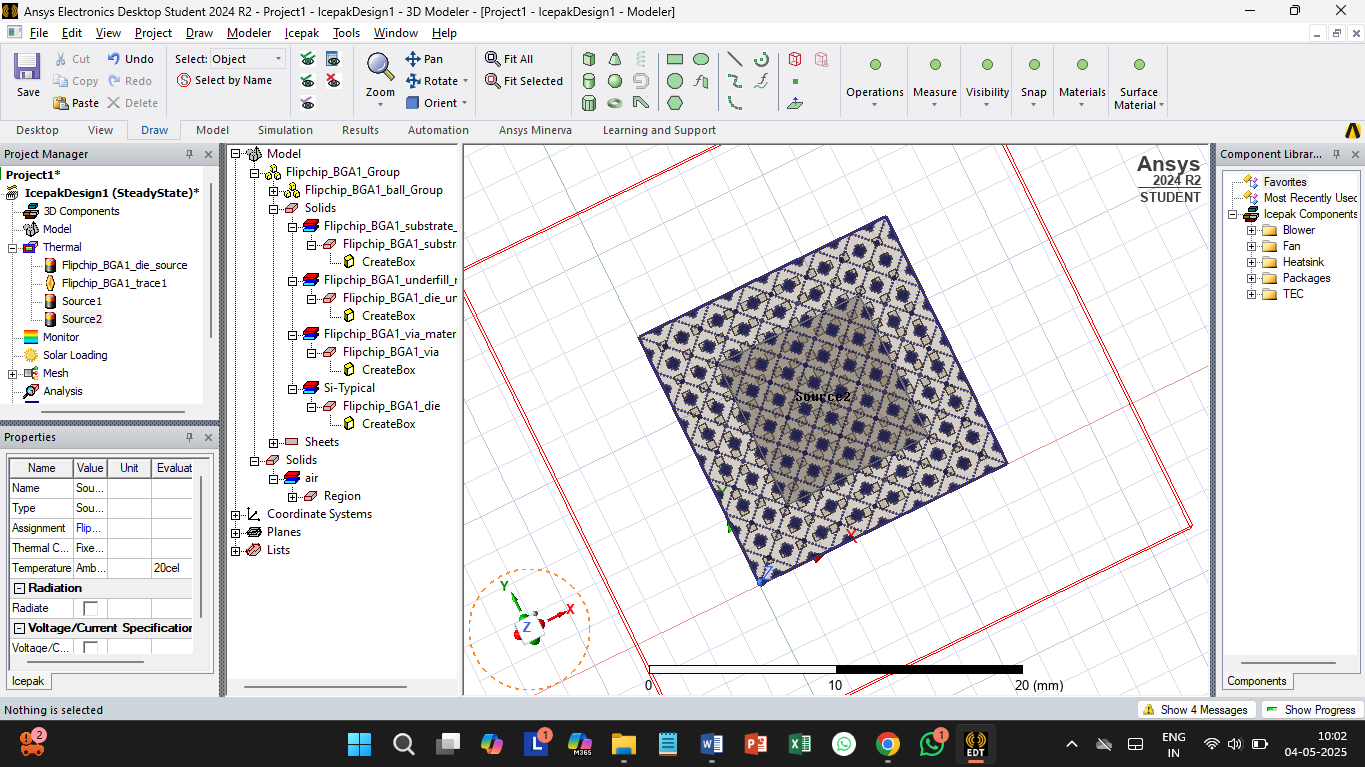
# *(Double click to access)*

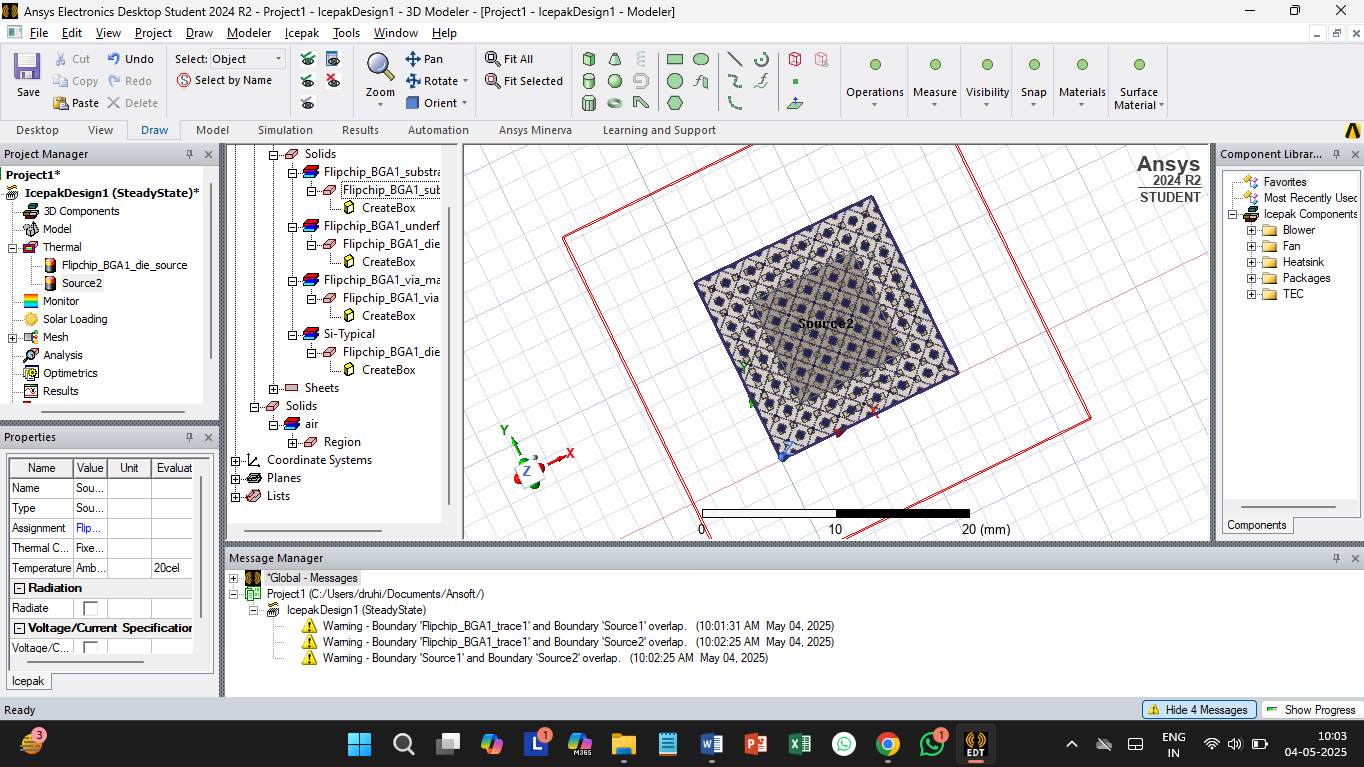
# Lesson 3

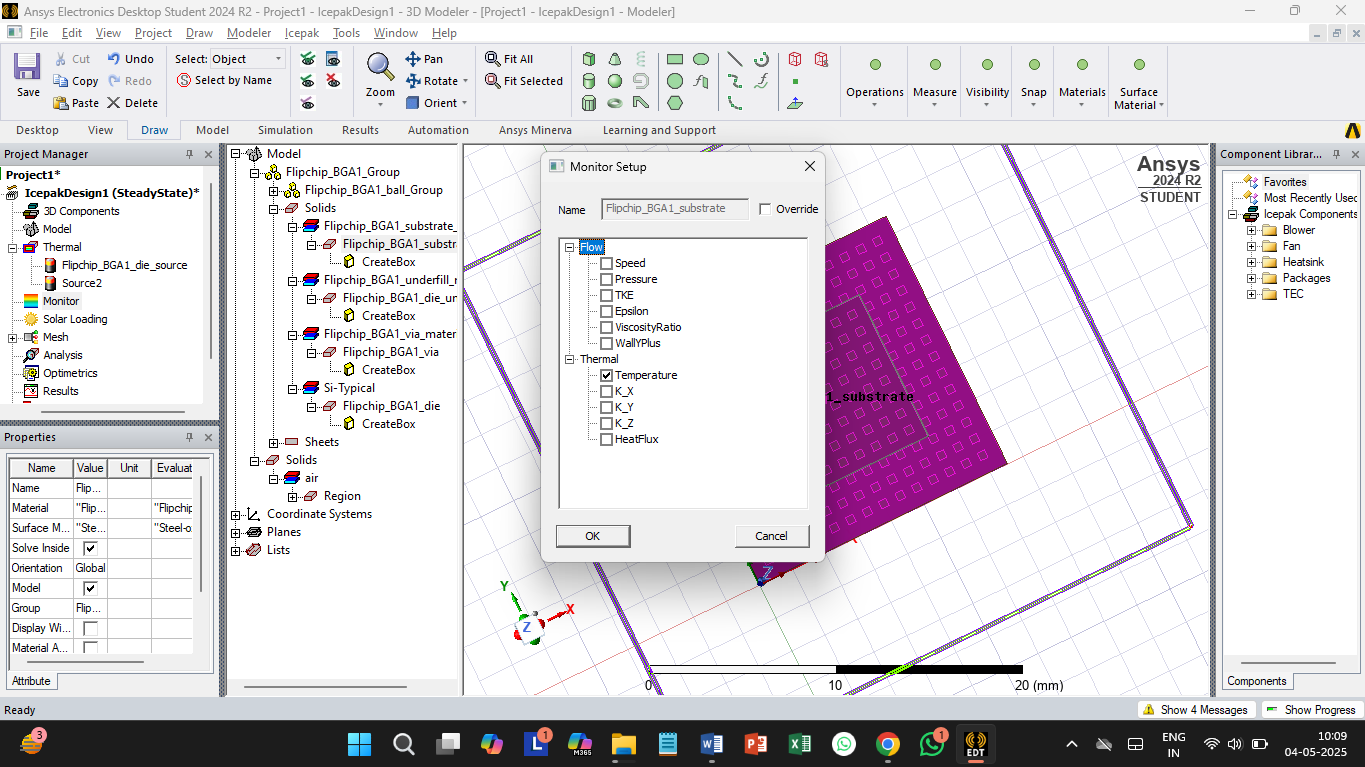


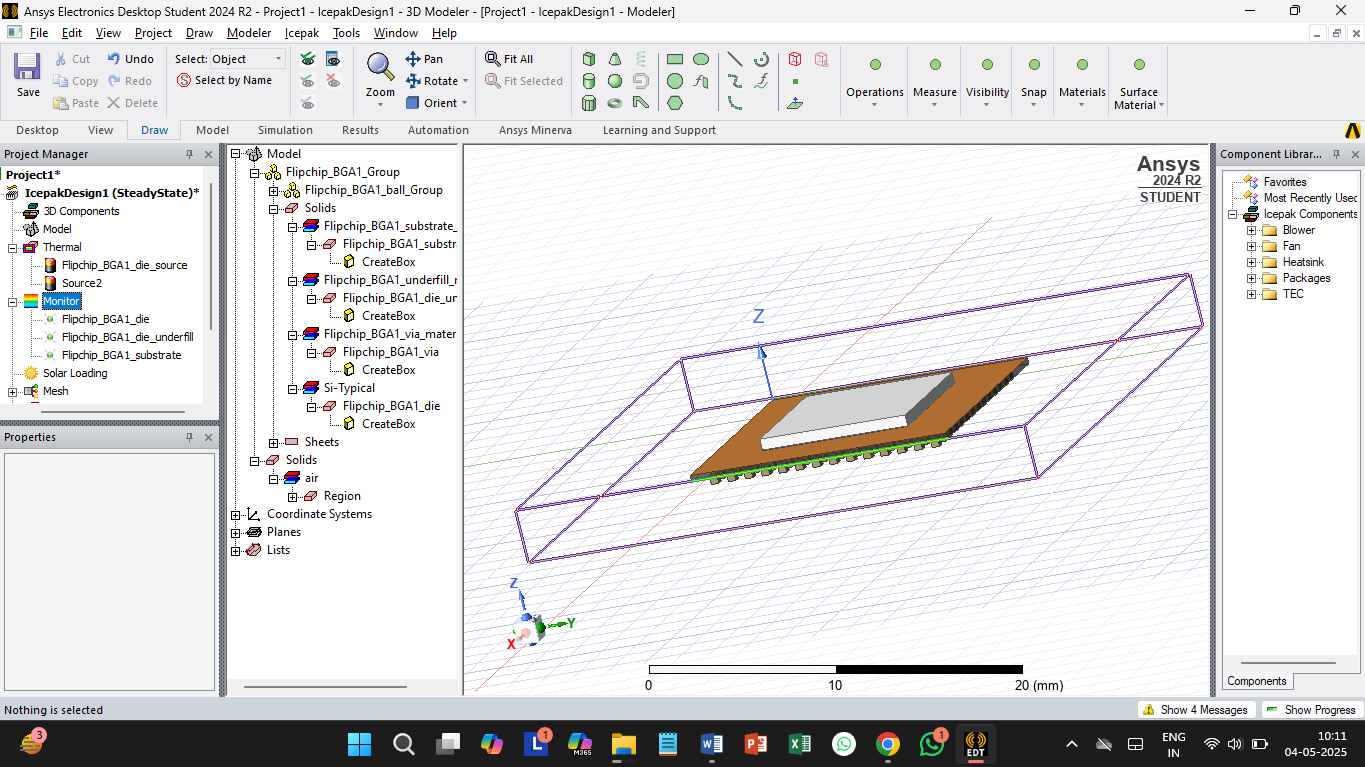








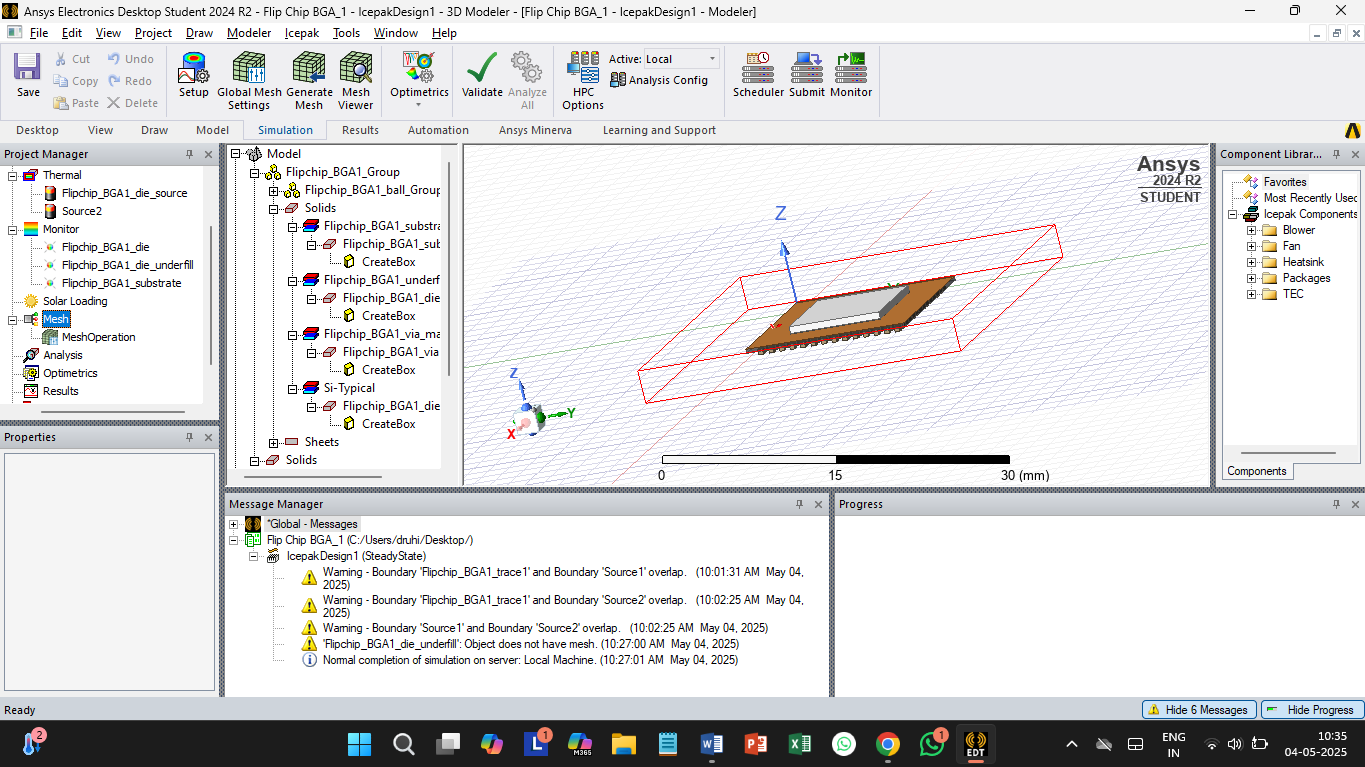
Trace and source 1 removed to avoid boundary overlap.



Monitors assigned to die, die underfill and substrate.

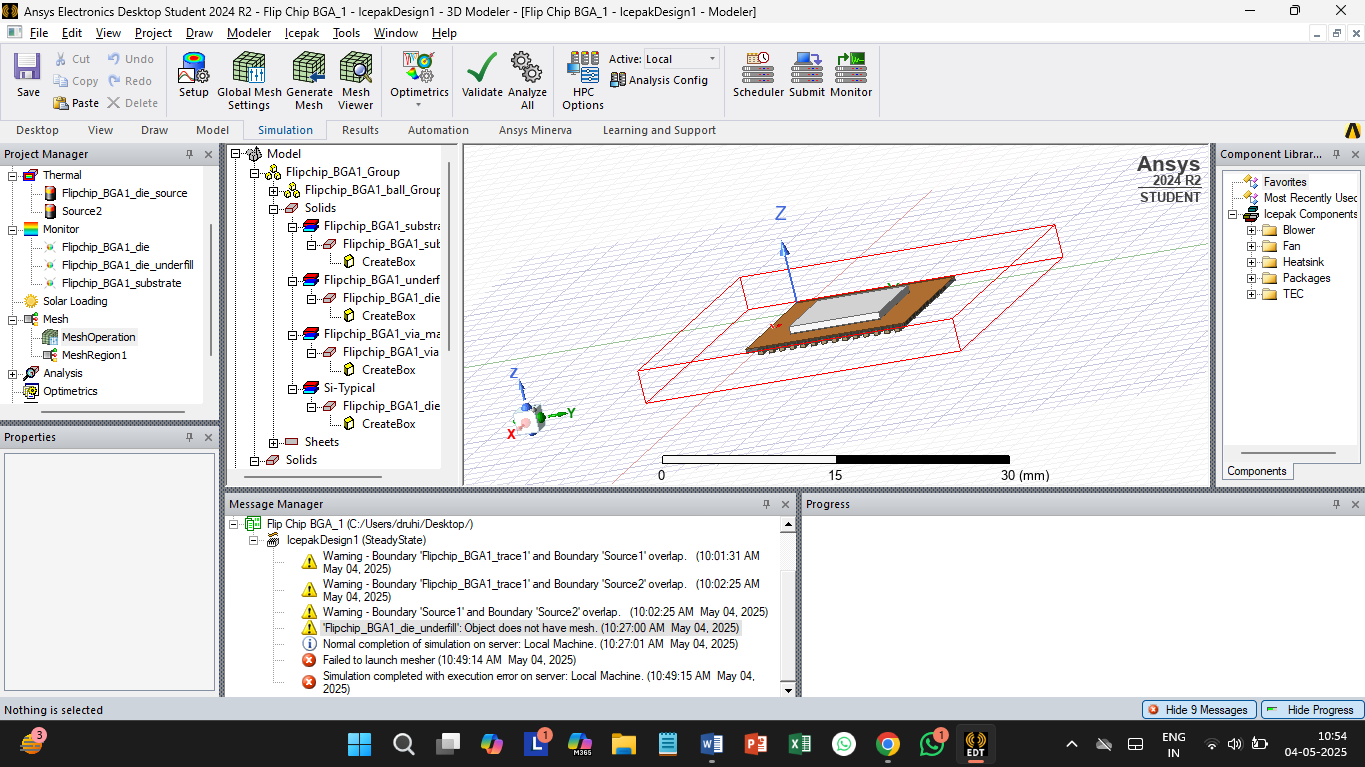
# Lesson 4

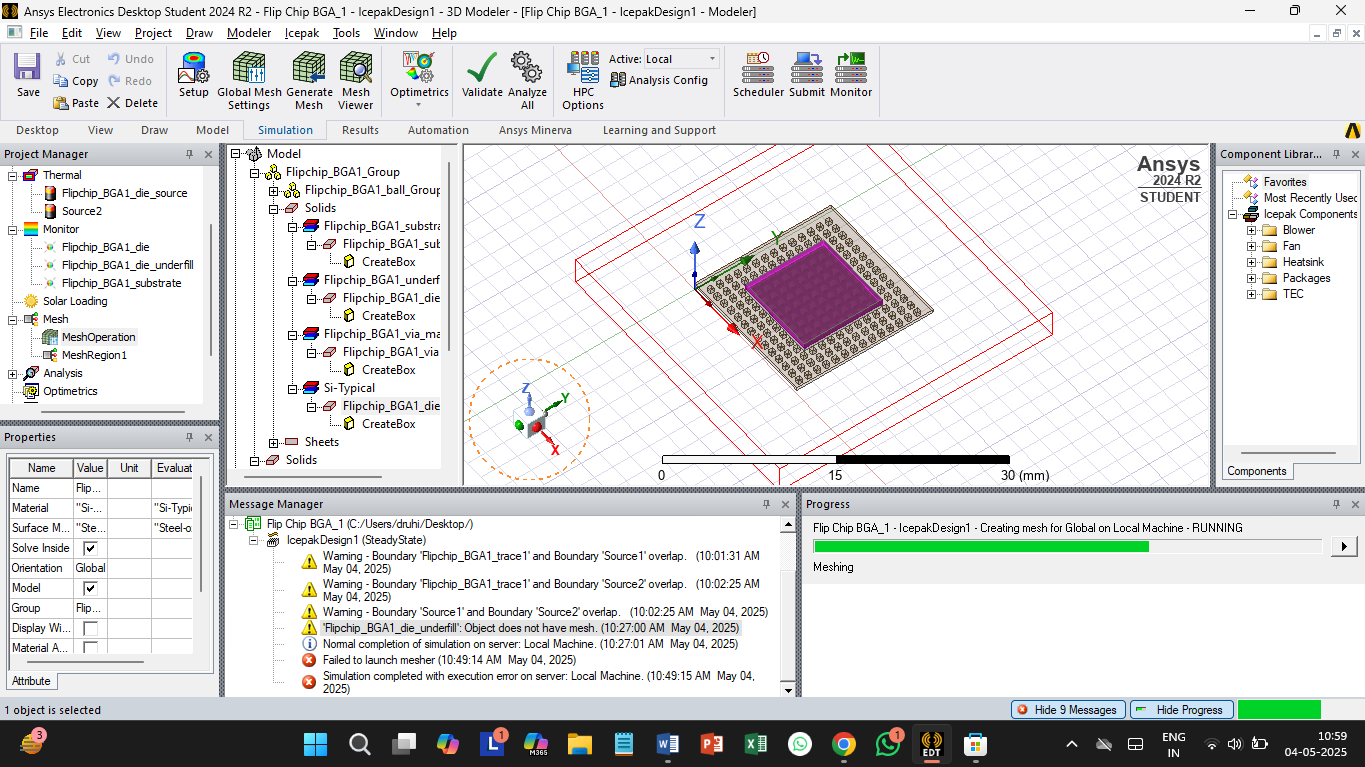
Mesh Generation Video

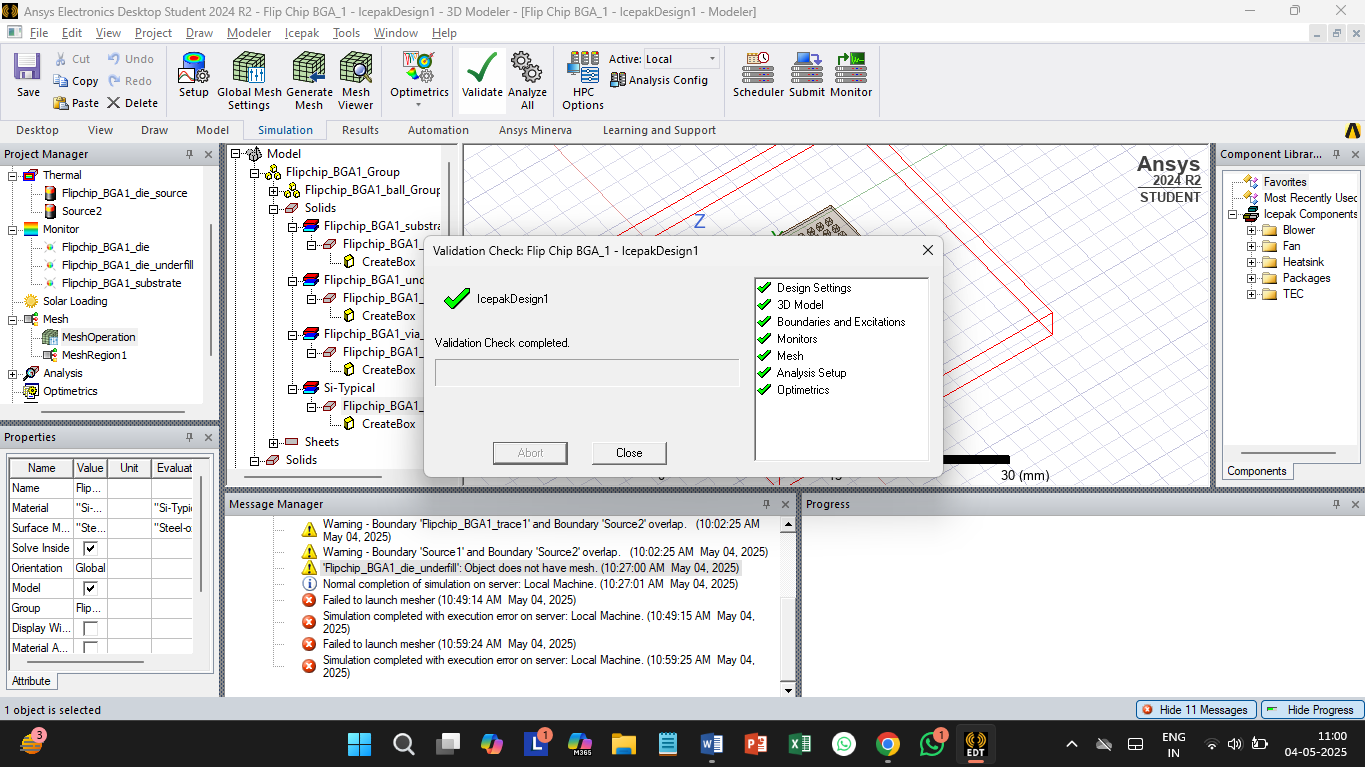
*(Double click to access)*

Analysis Validation done.

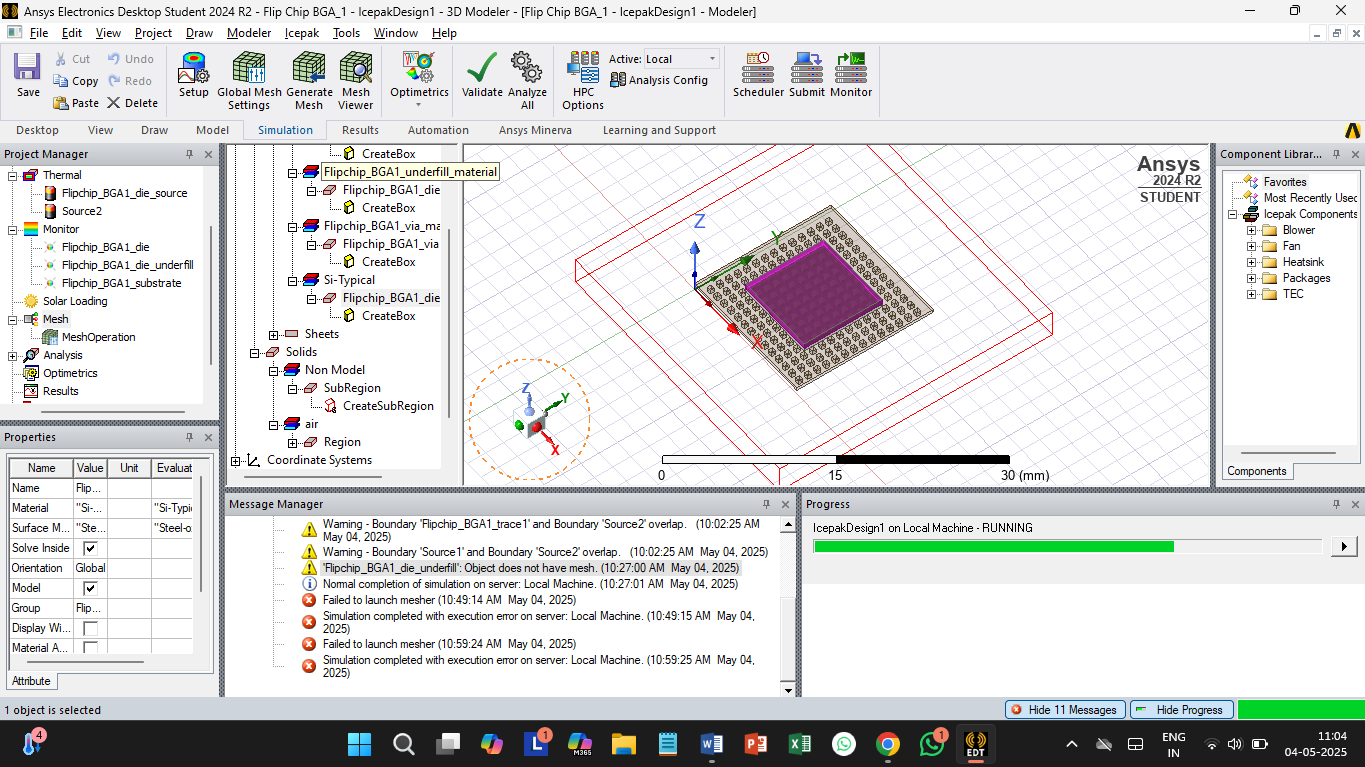
*(Double click to access)*

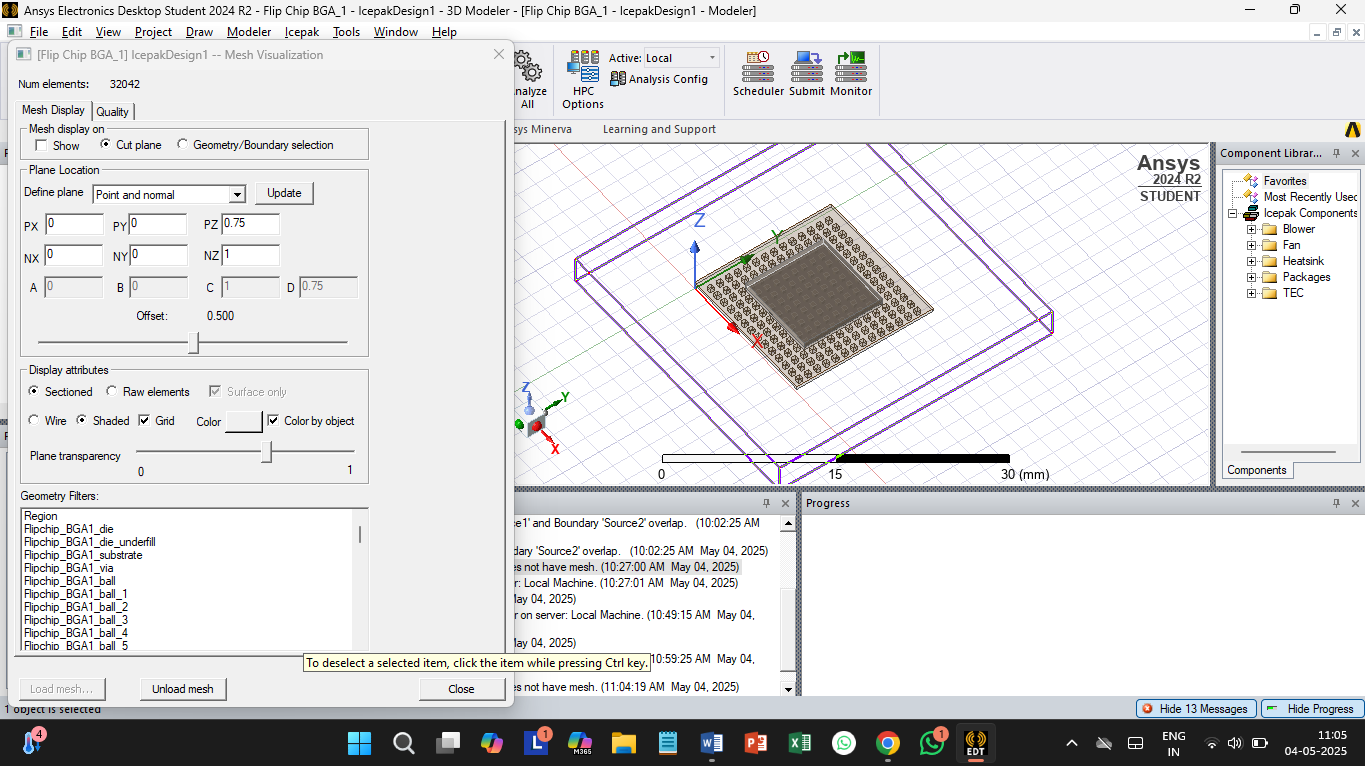
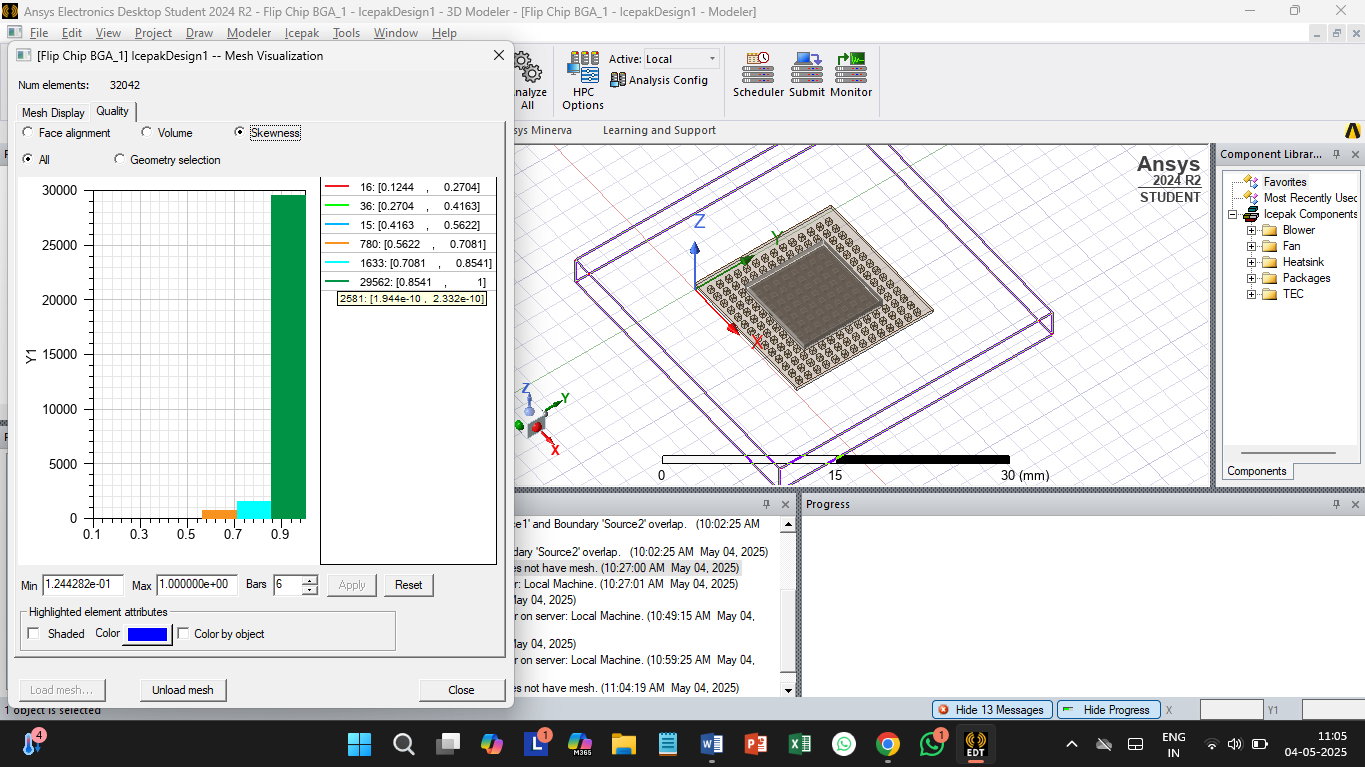
Regional mesh generation

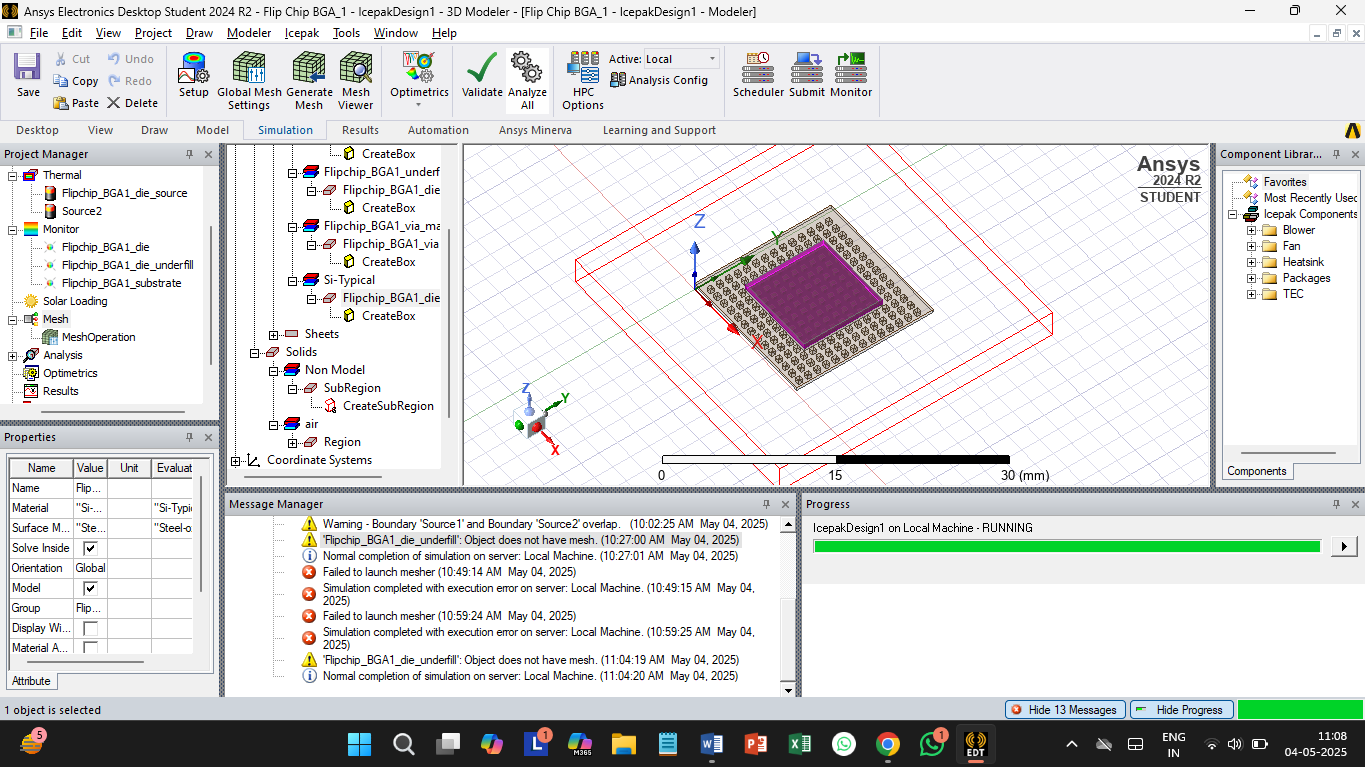
Mesh regeneration

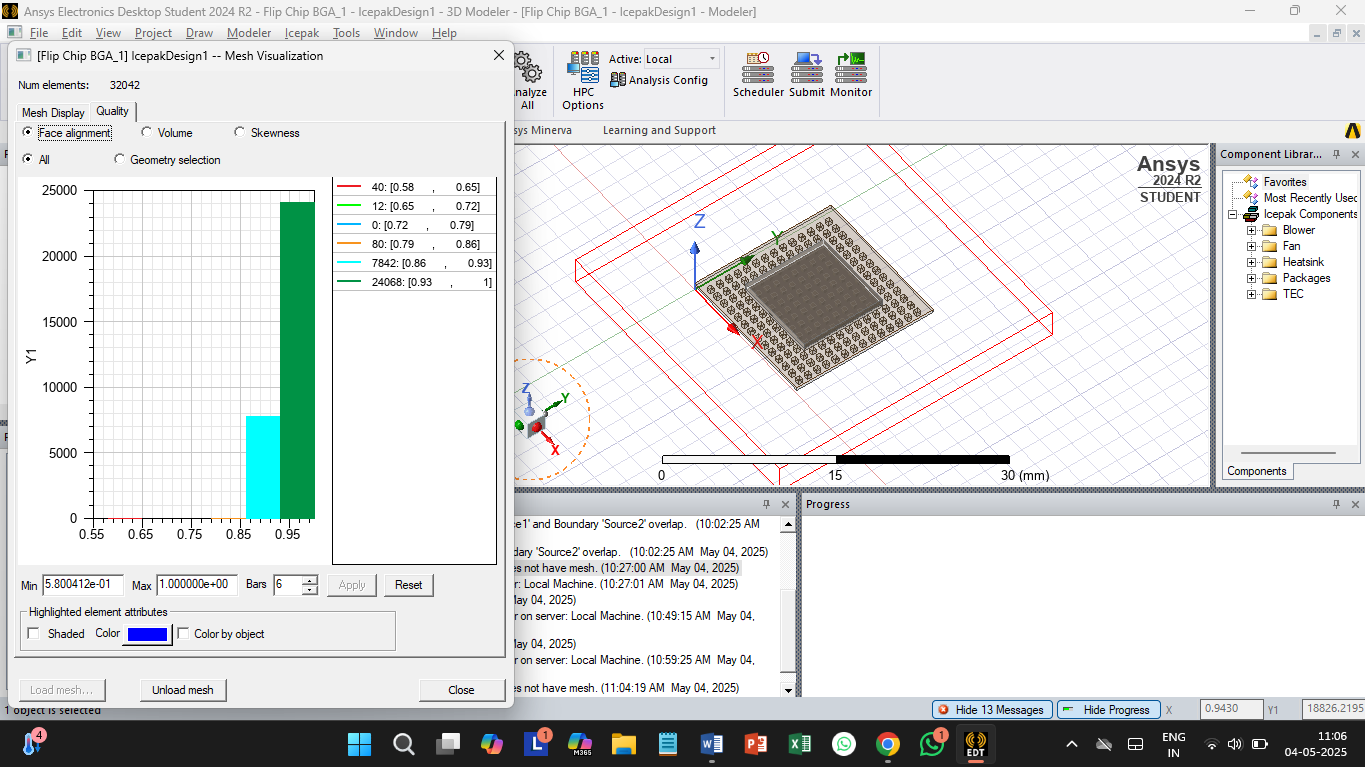
Validation

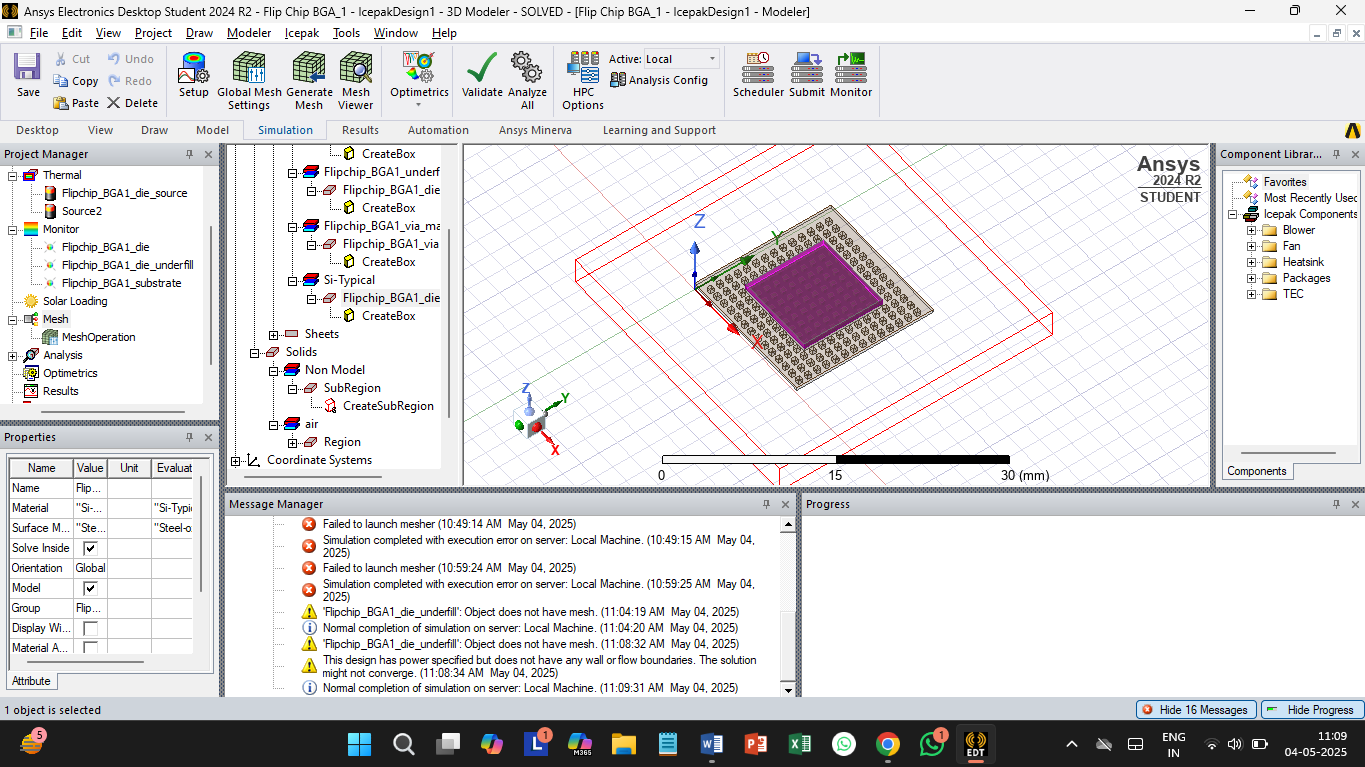
# Lesson 5

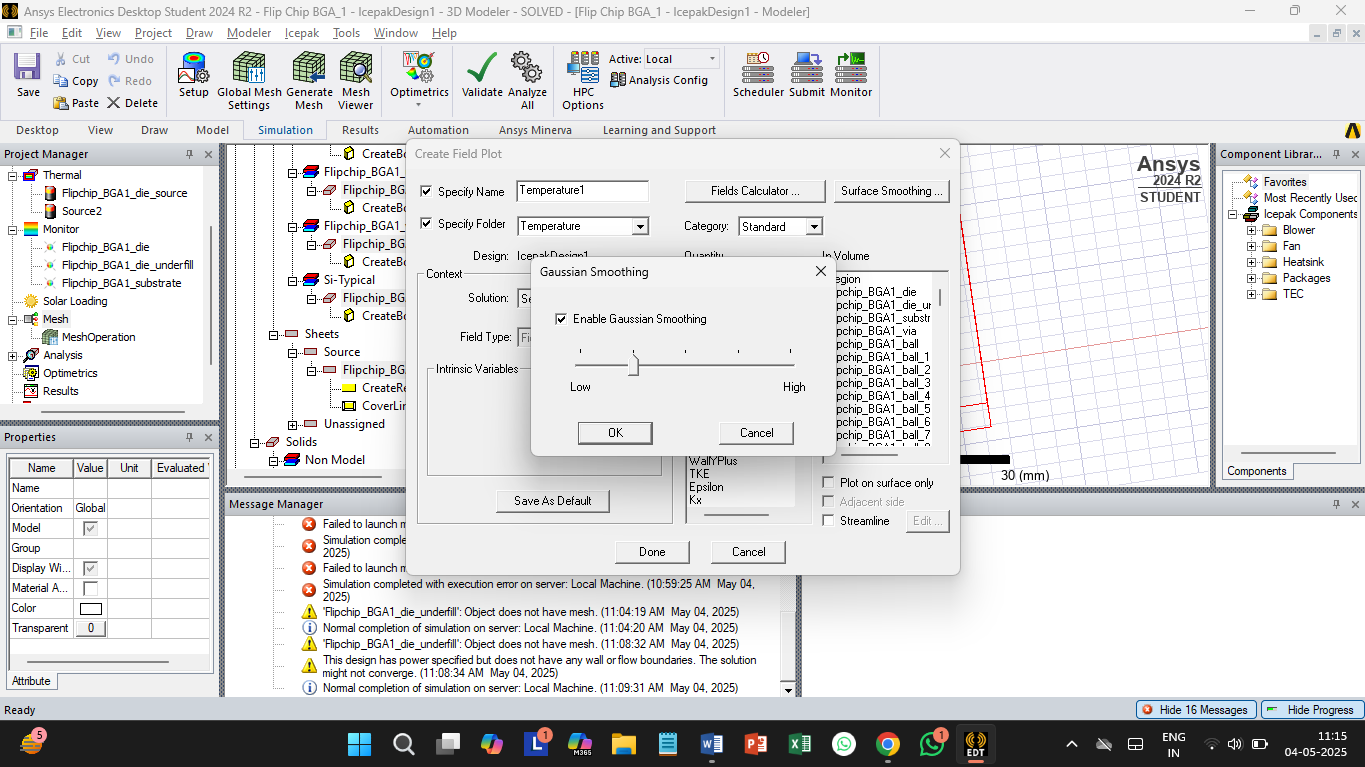
Regeneration of mesh after deleting the mesh region.

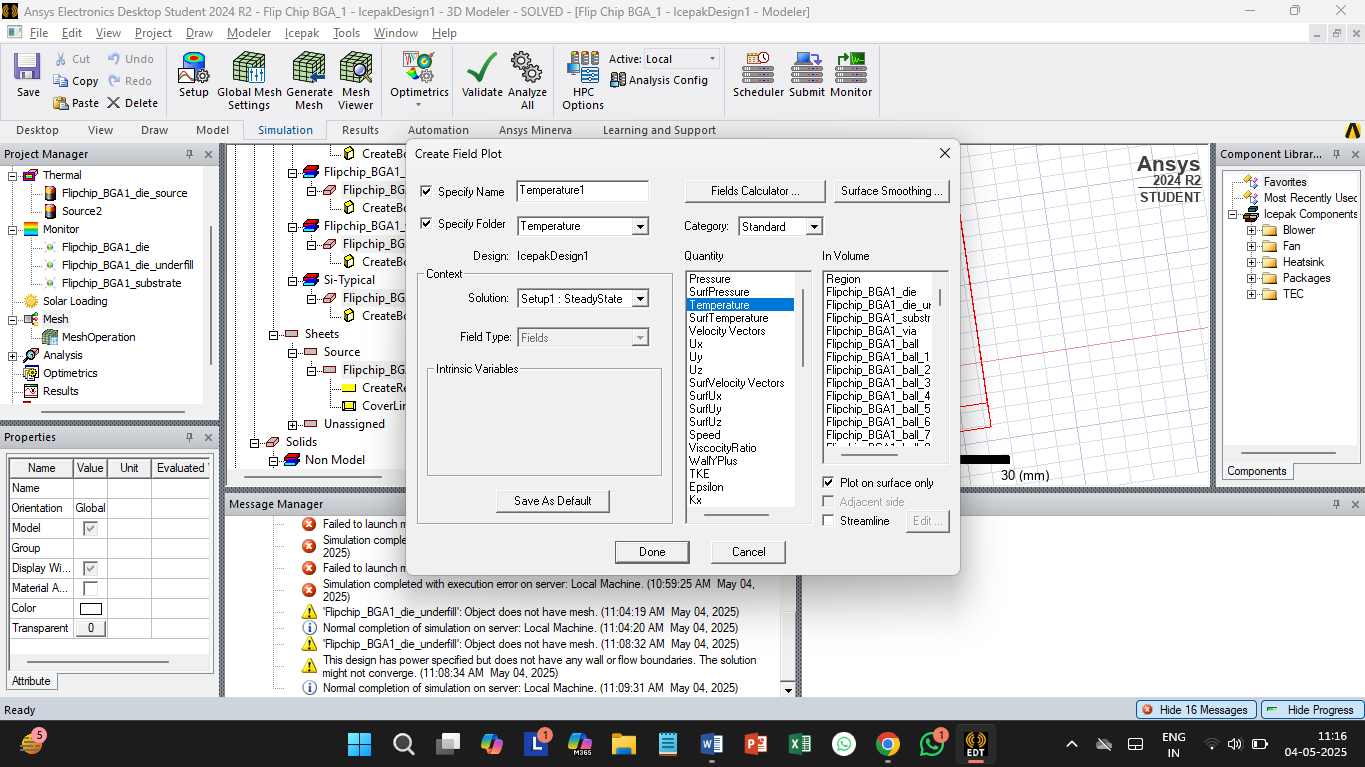


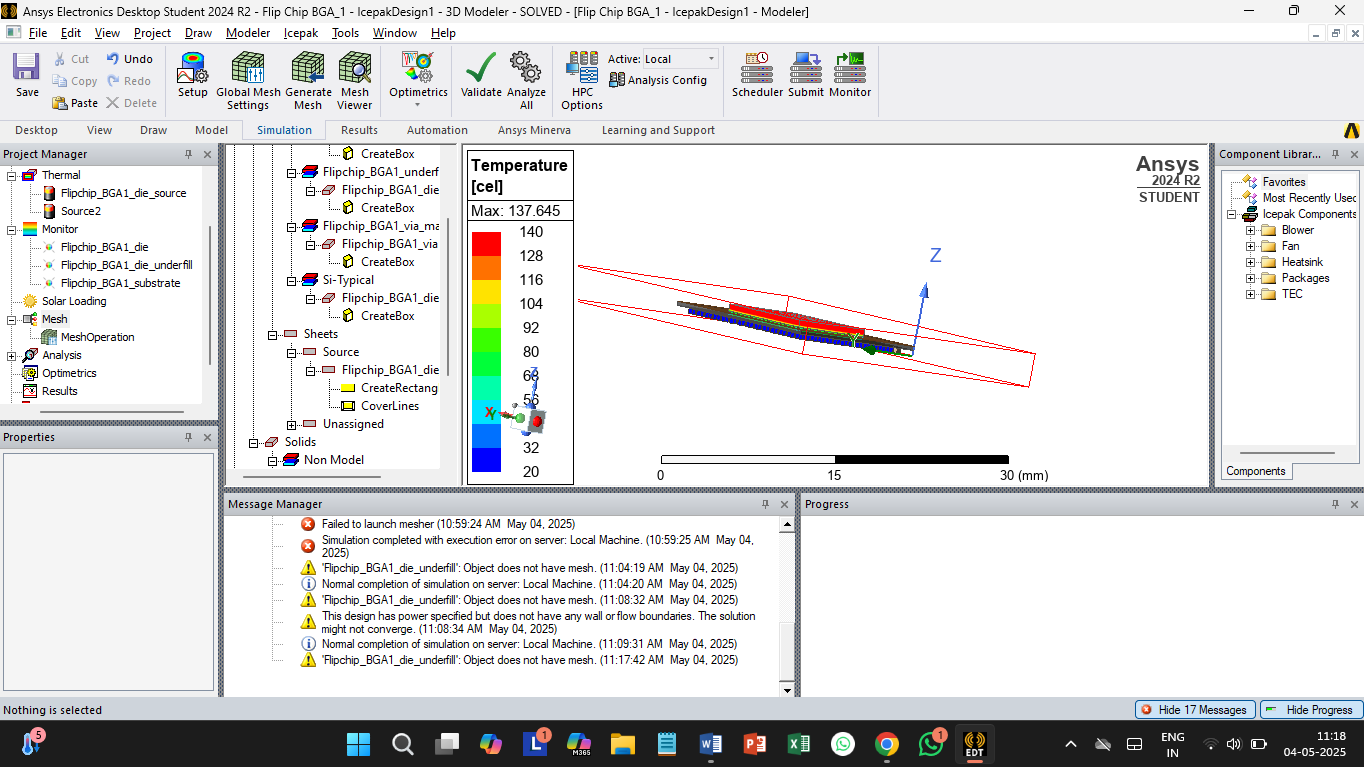
Analyse all









Temperature Map

